

PCB & IME

2027杭州国际PCB及智能制造设备展览会

2027 Hangzhou International PCB & Intelligent Manufacturing Equipment Expo

同期举办：第二届杭州国际半导体与集成电路创新展览会

The 2nd Hangzhou International Semiconductor & Integrated Circuit Industry Innovation Exhibition



2027.05.27-29

May 27-29, 2027



杭州大会展中心-浙江

Hangzhou Grand Convention and Exhibition Center, Zhejiang

主办及战略单位

Organizers & Strategic Partners

高登会展集团

Golden Conference & Exhibition Group

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Zhejiang Artificial Intelligence Society

浙江省半导体行业协会

Zhejiang Semiconductor Industry Association

浙江机器人产业发展协会

Zhejiang Robot Industry Association

浙江省计算机系统集成行业协会

Zhejiang Computer Information System Integration Industry Association

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ABOUT PCB & IME EXPO 2027

印制电路板被誉为“电子产品之母”，是芯片实现电气互联的核心载体。当AI算力奔涌而来，当新能源汽车疾驰向前，当第三代半导体重塑产业边界，国内高阶IC载板、高频高速板、高多层板需求持续走高，国产替代进程加速推进。“十五五”规划明确提出加快发展新一代智能制造，促进制造业“智改数转网联”，推动“人工智能+制造”加出新速度、新成效。在集成电路领域，规划纲要提出全链条推动关键核心技术攻关取得决定性突破。PCB产业作为电子信息制造业的基础环节，正迎来高端化、数智化、绿色化转型的政策窗口期。杭州及长三角地区为展会提供了坚实的产业腹地。杭州钱塘芯谷已集聚集成电路企业超140家，产业规模突破800亿元，晶圆制造能力占浙江省四分之一以上，是国内唯一同时具备4英寸至12英寸晶圆制造能力的区县。杭州市“智造社区”建设行动计划明确提出优化服务新一代半导体和集成电路、具身智能机器人等重点产业链核心制造环节。长三角地区集聚大量PCB成品厂、材料与装备企业，下游半导体、算力、新能源产业配套完善，具备得天独厚的产业区位优势。

Printed circuit boards (PCBs), often referred to as the “motherboards of electronic products,” are the core platform for electrical interconnection between chips and electronic systems. As AI computing power accelerates, new energy vehicles advance rapidly, and third-generation semiconductors reshape industry boundaries, demand for advanced IC substrates, high-frequency/high-speed PCBs, and high-layer-count boards continues to rise, accelerating the shift toward domestic alternatives. China's 15th Five-Year Plan calls for faster development of next-generation intelligent manufacturing, advancing the digital transformation, intelligent upgrading and networked integration of manufacturing, and driving new momentum through “AI + Manufacturing.” In the integrated circuit sector, the Plan also calls for breakthroughs in critical and core technologies across the entire value chain. As a foundational segment of electronic information manufacturing, the PCB industry is entering a strategic window for high-end, digital-intelligent and green transformation. Hangzhou and the Yangtze River Delta provide a strong industrial base for the Expo. Hangzhou's Qiantang Chip Valley is home to more than 140 integrated circuit companies, with the industry exceeding RMB 80 billion in scale. Its wafer manufacturing capacity accounts for more than one-quarter of Zhejiang Province's total, making it the only county-level administrative area in China with wafer manufacturing capabilities spanning 4-inch to 12-inch wafers. Hangzhou's “Intelligent Manufacturing Community” Development Action Plan calls for enhanced support for core manufacturing segments across key industrial value chains, including next-generation semiconductors and integrated circuits and embodied intelligent robotics. The Yangtze River Delta is home to a large concentration of PCB manufacturers, materials and equipment suppliers, supported by well-developed downstream ecosystems in semiconductors, AI computing and new energy. This integrated industrial landscape gives the region a distinctive location advantage and provides a strong foundation for the development of the PCB and intelligent manufacturing industries.

ABOUT PCB & IME EXPO 2027

AI算力正把PCB需求快速推向高多层、高频、高速方向，行业增长逻辑正由规模扩张转向技术提升。在这一产业变革的关键节点，高登会展联合相关行业主管机构定于2027年5月27日至29日在杭州大会展中心召开“2027杭州国际PCB及智能制造设备展览会”，并与第二届杭州国际半导体与集成电路产业创新展览会（杭州长芯展）同期同馆举办。本展会定位为长芯展核心配套子展，聚焦PCB全产业链及智能制造设备，补齐“芯片—基板—硬件制造”关键一环。与长芯展主展半导体全产业链深度协同：长芯主展汇聚IC设计、晶圆制造、先进封装、Chiplet、第三代半导体、AI芯片企业，大量芯片企业亟待寻找可靠的IC载板、高频高速PCB供应链；PCB展区实现上游芯片企业与PCB/载板、智能制造装备企业面对面对接，打通从芯片设计到硬件制造的完整链路。展会重点展示钻孔、曝光、电镀、蚀刻、成型、检测、自动化产线、MES、工业互联网、AI质检等智能制造设备与方案，助力PCB企业降本增效、提升良率、加快数字化转型。旨在补齐“芯片设计—晶圆制造—先进封装—IC载板/PCB—终端硬件”全产业链展示链路中的关键一环，搭建PCB与半导体产业精准对接平台，推动高端IC载板与智能制造装备的国产化突破，为长三角乃至全国电子电路产业的高质量发展注入新动能。

AI computing is rapidly driving PCB demand toward higher layer counts, higher frequencies and higher speeds, shifting the industry's growth model from scale expansion to technology advancement. At this critical stage of industrial transformation, Golden Conference & Exhibition Group, together with relevant industry authorities and organizations, will host the 2027 Hangzhou International PCB & Intelligent Manufacturing Equipment Expo from May 27–29, 2027, at the Hangzhou Grand Convention & Exhibition Center. The Expo will be held concurrently and in the same venue as The 2nd Hangzhou International Semiconductor & Integrated Circuit Industry Innovation Exhibition (SICE). Positioned as a core supporting event of the SICE, the PCB Expo will focus on the entire PCB value chain and intelligent manufacturing equipment, addressing a critical link between chips, substrates and hardware manufacturing. The Expo will work in close synergy with the Changxin Expo's semiconductor value chain. The main expo will bring together companies across IC design, wafer manufacturing, advanced packaging, Chiplet, third-generation semiconductors and AI chips, many of which are seeking reliable supply chains for IC substrates and high-frequency/high-speed PCBs. The PCB Expo will facilitate face-to-face business matchmaking between upstream chip companies and PCB/IC substrate manufacturers and intelligent manufacturing equipment suppliers, connecting the full chain from chip design to hardware manufacturing. Key exhibits will include intelligent manufacturing equipment and solutions for drilling, exposure, electroplating, etching, forming, inspection and testing, automated production lines, MES, industrial internet and AI-powered quality inspection, helping PCB manufacturers reduce costs, improve efficiency and yield, and accelerate digital transformation. The Expo aims to complete the critical link in the exhibition chain spanning chip design → wafer manufacturing → advanced packaging → IC substrates/PCBs → end-product hardware, while creating a targeted matchmaking platform connecting the PCB and semiconductor industries. It will support advances in the domestic development of high-end IC substrates and intelligent manufacturing equipment, injecting new momentum into the high-quality development of the electronic circuit industry across the Yangtze River Delta and China.

Concurrent Events

同期活动

展会同期将举办PCB智能制造与IC载板产业高峰论坛、IC载板技术与国产化替代研讨会、PCB智能制造与数字化转型论坛、PCB绿色制造与可持续发展论坛等多场高规格专业活动，汇聚行业领袖、技术专家与产业资本，共话前沿趋势。同时设置PCB/载板专场供需对接会，定向邀请半导体企业、下游终端制造商、科研院所与投资机构面对面洽谈，推动技术交流与商务合作精准落地，让参展参会更具实效。

The Expo will feature a series of high-level professional events, including the PCB Intelligent Manufacturing & IC Substrate Industry Summit, IC Substrate Technology & Domestic Development Seminar, PCB Intelligent Manufacturing & Digital Transformation Forum, and PCB Green Manufacturing & Sustainable Development Forum. Industry leaders, technology experts and investors will come together to explore emerging trends and opportunities across the sector. A dedicated PCB/IC Substrate Supply-Demand Matchmaking Session will also be held, bringing together semiconductor companies, downstream manufacturers, research institutes and investment institutions for targeted, face-to-face discussions. The program is designed to facilitate focused technical exchange, accelerate business cooperation and deliver tangible outcomes for exhibitors and participants.



PCB智能制造与IC载板产业高峰论坛
PCB Intelligent Manufacturing & IC Substrate Industry Summit



IC载板技术与国产化替代研讨会
IC Substrate Technology & Domestic Development Seminar



PCB智能制造与数字化转型论坛
PCB Intelligent Manufacturing & Digital Transformation Forum



PCB绿色制造与可持续发展论坛
PCB Green Manufacturing & Sustainable Development Forum

电路板成品展示区 *Finished PCB Products*

刚性PCB、柔性FPC、刚挠结合板、高频高速板、厚铜板、特种电路板、IC载板（BT/ABF）等

Rigid PCBs, flexible PCBs (FPCs), rigid-flex PCBs, high-frequency/high-speed PCBs, heavy-copper PCBs, specialty PCBs, IC substrates (BT/ABF), and more.

PCB关键原辅材料区 *Key PCB Materials & Chemicals*

覆铜板、半固化片、铜箔、油墨、干膜、防焊漆、电镀化学品、特种树脂等

Copper-clad laminates (CCLs), prepregs, copper foil, inks, dry films, solder masks, plating chemicals, specialty resins, and other key materials and chemicals.

智能制造工艺设备区 *Intelligent Manufacturing Process Equipment*

钻孔、电镀、压合、蚀刻、曝光、成型、激光加工等设备

Drilling, electroplating, lamination, etching, exposure, forming, laser processing and other PCB manufacturing equipment.

检测与测试设备区 *Inspection & Testing Equipment*

AOI、AXI、阻抗测试、飞针测试、在线检测系统等

Automated optical inspection (AOI), automated X-ray inspection (AXI), impedance testing, flying probe testing, in-line inspection systems and other testing and inspection solutions.

自动化产线与数字化方案区 *Automated Production Lines & Digital Solutions*

自动化生产线、AGV物流、MES、工业互联网、AI质量管控、环保处理方案等

Automated production lines, AGV logistics systems, manufacturing execution systems (MES), industrial internet platforms, AI-powered quality control, environmental protection and waste treatment solutions, and more.

供需对接与产业服务区 *Business Matchmaking & Industry Services*

封闭洽谈、产业招商、人才对接、投融资对接

Closed-door business meetings, investment attraction, talent matchmaking, investment and financing matchmaking, and related industry services.



Participation Fees

展会费用

企业性质 Company Type	展位类别 Booth Type	展位费用 Booth Fee
国内企业 For domestic enterprises	室内光地 Indoor Raw Space	1600(RMB)/m ² /展期/Expo
	标准展位 Standard Booths	16800(RMB)/3mx3m/展期/Expo
国外企业 For overseas enterprises	室内光地 Indoor Raw Space	480(USD)/m ² /展期/Expo
	标准展位 Standard Booths	4800(USD)/3mx3m/展期/Expo

Note: The raw space (minimum 36 sq.m.) only supplies a show space excluding stand frames, show equipment, carpet and power supply, etc.

注：(最少36平方米起租) “光地”只提供参展面积，不包括展架、展具、地毯、电源等。

赞助方案 SPONSORSHIP PROPOSAL

01 赞助条例 Sponsorship Packages

赞助项目	金额(万元)	规格/权益说明	限量
展会协办冠名	60	展会协办单位	独家
展会支持单位	40	展会支持单位	限3家
钻石•独家总冠名赞助	168	享有XX品牌之夜	独家
黄金•战略合作赞助	138	享有晚宴VIP独立餐桌与现场展示位	限3家
白银•战略合作赞助	98	享有晚宴标准席位与官方荣誉证书	限6家
指定品类•专项赞助	38	享有晚宴品类独家冠名	独家

Sponsorship Item	Amount (10K RMB)	Specifications / Benefits	Availability
Exhibition Co-organizer Title	60	Exhibition Co-organizer	Exclusive
Exhibition Support Partner	40	Exhibition Supporter	Limited to 3
Diamond - Exclusive Title Sponsor	168	Includes "[Brand Name] Night"	Exclusive
Gold - Strategic Partner	138	VIP dinner table + on-site display booth	Limited to 3
Silver - Strategic Partner	98	Standard dinner seat + official certificate	Limited to 6
Designated Category Sponsor	38	Exclusive category naming rights at dinner	Exclusive

02 外墙广告 Exterior Wall Ads

赞助项目	金额(万元)	规格/权益说明	限量
东登录厅广场广告	80	25.3m×6m入口上方玻璃贴纸	独家
东登录厅广场两侧桁架广告	10	5m×3m两侧桁架	限6家
东登录厅广场左右两侧广告	30	18.1m×15m墙贴	限2家
东登录厅内左右两侧广告	20	18.3m×6m墙贴	限2家
东登录厅正面二层广告	60	13.66m×3.5m墙贴	独家
东/中登录厅展厅通道入口广告	30	20.2m×6m玻璃贴	限2家
中登录厅左右两侧墙面广告	20	55Lm×3.5Hm	限2家
商业通道一层吊旗广告	15	5m×1.5m吊旗	限4家
商业通道一层方形包柱广告	5	1.6×3m方形包柱	限10家
Sponsorship Item	Amount (10K RMB)	Specifications / Benefits	Availability
East Hall Plaza Billboard	80	25.3mx6m entrance glass sticker	Exclusive
East Hall Plaza Truss Ads (both sides)	10	5mx3m truss on both sides	Limited to 6
East Hall Plaza Left & Right Wall Ads	30	18.1mx15m wall sticker	Limited to 2
East Hall Interior Left & Right Wall Ads	20	18.3mx6m wall sticker	Limited to 2
East Hall 2nd Floor Front Wall Ad	60	13.66mx3.5m wall sticker	Exclusive
East/Central Hall Corridor Entrance Ad	30	20.2mx6m glass sticker	Limited to 2
Central Hall Left & Right Wall Ads	20	55Lmx3.5Hm	Limited to 2
Commercial Corridor 1F Hanging Flag Ads	15	5mx1.5m hanging flag	Limited to 4
Commercial Corridor 1F Square Pillar Ads	5	1.6mx3m square pillar	Limited to 10

03 馆内外广告 Indoor/Outdoor Hall Ads

赞助项目	金额(万元)	规格/权益说明	限量
2号展厅入口吊旗广告	12	4m×1.5m 6个吊旗	独家
2号展厅入口两侧桁架广告	6	5m×3m桁架	限2家
2号展厅入口门口广告	10	3L×3Hm/5L×3H	独家
2号展厅内部出入口横幅广告	20	17.6m×2.1m墙贴	独家
2号展厅内部出入口包柱广告	12	3m×6m 6个柱子	独家
2号展厅入口右边拐墙贴广告	15	12.2m×10.7m墙贴	独家
2号展厅内部吊旗广告	5	5m×3m 9个吊旗	限9家
Sponsorship Item	Amount (10K RMB)	Specifications / Benefits	Availability
Hall 2 Entrance Hanging Flag Ads	12	4mx1.5m (6 flags)	Exclusive
Hall 2 Entrance Truss Ads (both sides)	6	5mx3m truss	Limited to 2
Hall 2 Entrance Door Ad	10	3Lx3Hm/5Lx3Hm	Exclusive
Hall 2 Interior Entrance Banner Ad	20	17.6mx2.1m wall sticker	Exclusive
Hall 2 Interior Entrance Pillar Ads	12	3mx6m (6 pillars)	Exclusive
Hall 2 Entrance Right Corner Wall Ad	15	12.2mx10.7m wall sticker	Exclusive
Hall 2 Interior Hanging Flag Ads	5	5mx3m (9 flags)	Limited to 9

04

登录大厅广告 Lobby Ads

赞助项目	金额(万元)	规格/权益说明	限量
东登录大厅入口LED屏	40	24.96m×1.28m, 人流最密集处	独家
中登录大厅入口LED屏	30	24.96m×1.6m, 第一视觉冲击	独家
展厅主通道喷绘广告	15	4m×7m, 主通道核心位置	限8家
展厅外门口两侧喷绘广告	10	3m×5m, 入口处两边位置	限8家
展厅之间通道喷绘广告	10	3m×6m, 通道两边位置	限24家

Sponsorship Item	Amount (10K RMB)	Specifications / Benefits	Availability
East Lobby Entrance LED Screen	40	24.96mx1.28m, highest foot traffic	Exclusive
Central Lobby Entrance LED Screen	30	24.96mx1.6m, first visual impact	Exclusive
Main Hallway Banner Ad	15	4mx7m, core location	Limited to 8
Hall Entrance Side Banner Ads	10	3mx5m, both sides of entrance	Limited to 8
Hall-to-Hall Corridor Banner Ads	10	3mx6m, both sides of corridor	Limited to 24

05

会议广告 Conference Ads

赞助项目	金额(万元)	规格/权益说明	限量
论坛大屏两侧广告	40	3.5m×2m, 入口处两边位置	限2家
论坛外侧单面广告	15	2m×2m, 入口处两边位置	限10家
论坛椅背套广告位	10	论坛3天参会嘉宾宣传推广	独家
平行论坛	15	分论坛冠名	独家
专场发布会(1.5小时)	6	提供场地、设备及宣传组织	多家
海外买家对接会	0.35	与海外买家精准对接	多家

Sponsorship Item	Amount (10K RMB)	Specifications / Benefits	Availability
Forum Main Stage Side Ads	40	3.5mx2m, entrance sides	Limited to 2
Forum External Single-sided Ad	15	2mx2m, entrance sides	Limited to 10
Forum Chair Back Cover Ad	10	3-day promotion to attendees	Exclusive
Parallel Forum	15	Sub-forum naming rights	Exclusive
Exclusive Press Conference (1.5h)	6	Venue, equipment, promotion	Multiple
Overseas Buyer Matchmaking	0.35	Direct engagement with overseas buyers	Multiple

06

视频广告 Video Ads

赞助项目	金额(万元)	规格/权益说明	限量
深度专访	1.2	3分钟剪辑成片+官媒宣发	多家
展商推荐	6	45秒剪辑成片+官媒宣发	多家

Sponsorship Item	Amount (10K RMB)	Specifications / Benefits	Availability
In-depth Interview	1.2	3-min edited video + official media release	Multiple
Exhibitor Feature	6	45-sec edited video + official media release	Multiple

07

印刷广告 Print Ads

赞助项目	金额(万元)	规格/权益说明	限量
参观指南封面广告	15	最高级别印刷品曝光	独家
参观指南封底广告	10	次高级别印刷品曝光	独家
参观指南内页广告	5	精准投放至所有观众	限8家
展商/VIP证赞助	15	单面, 品牌伴随全程	独家

Sponsorship Item	Amount (10K RMB)	Specifications / Benefits	Availability
Visitor Guide Cover Ad	15	Top-tier print exposure	Exclusive
Visitor Guide Back Cover Ad	10	Second-tier print exposure	Exclusive
Visitor Guide Inside Page Ad	5	Targeted reach to all attendees	Limited to 8
Exhibitor/VIP Badge Sponsor	15	Single side, brand visibility throughout	Exclusive

08

品类广告 Category Ads

赞助项目	金额(万元)	规格/权益说明	限量
服装赞助	15	工作人员服装	独家
礼品袋赞助	30	约2万个移动的广告	独家
礼品赞助	20	约2万个展会赠品	独家
伴手礼赞助	30	约1000个嘉宾赠送	独家
咖啡/饮品赞助	10	VIP与海外买家见面会休息区	独家
饮用水赞助	10	瓶身贴标, 品牌触达高频	限2家
奖杯/奖牌/证书赞助	10	优秀展商与合作伙伴授牌	独家
官方指定用车	6	嘉宾接送	独家
合作银行	10	提供相关金融服务	独家
合作航空	20	提供日韩等国航空服务	独家
官方推文合作	5	官方公众号头条发布	多家
官方推文合作	3	官方公众号普通发布	多家

Sponsorship Item	Amount (10K RMB)	Specifications / Benefits	Availability
Apparel Sponsor	15	Staff uniforms	Exclusive
Gift Bag Sponsor	30	~20,000 mobile ads	Exclusive
Giveaway Sponsor	20	~20,000 expo giveaways	Exclusive
Souvenir Sponsor	30	~1,000 gifts for VIPs	Exclusive
Coffee/Beverage Sponsor	10	VIP & overseas buyer lounge	Exclusive
Drinking Water Sponsor	10	Bottle labels, high-frequency brand exposure	Limited to 2
Trophy/Medal/Certificate Sponsor	10	Awards for outstanding exhibitors & partners	Exclusive
Official Designated Vehicle	6	VIP shuttle service	Exclusive
Partner Bank	10	Financial services	Exclusive
Partner Airline	20	Air travel services for Japan, South Korea, etc.	Exclusive
Official WeChat Post Partnership	5	Headline post on official public account	Multiple
Official WeChat Post Partnership	3	Standard post on official public account	Multiple

Target Audience 目标观众

组委会精准邀约全球电子信息产业核心力量：涵盖IC设计、先进封装、Chiplet、第三代半导体、功率器件、AI/存储芯片等半导体采购研发人员；PCB/FPC/IC载板、覆铜板及材料厂商设备采购、工艺研发与质量部门；AI服务器、算力硬件、新能源汽车电子、通信、工控、消费电子终端制造商；汽车电子、医疗电子、航空航天、海洋电子方案商；以及软件生态、科研院所、高校、园区、投资机构、产业基金、政府主管部门及行业组织。

The Organizing Committee will conduct targeted outreach to key players across the global electronic information industry, including procurement and R&D professionals from IC design, advanced packaging, Chiplet, third-generation semiconductors, power devices, and AI and memory chip companies. The outreach will also cover procurement, process R&D and quality management professionals from PCB, FPC and IC substrate manufacturers, copper-clad laminate and material suppliers, and equipment providers; AI server, computing hardware, new energy vehicle electronics, communications, industrial control and consumer electronics manufacturers; and solution providers serving automotive electronics, medical electronics, aerospace and marine electronics. Other target groups include software ecosystem companies, research institutes, universities, industrial parks, investment institutions, industrial funds, government authorities and industry organizations.

立即注册 | Booth Registration

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To book a booth at the PCB & IME Expo 2027 or for more information, please email us immediately at info@goldenexpo.com.cn, or use the contact details below to reserve your space.

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